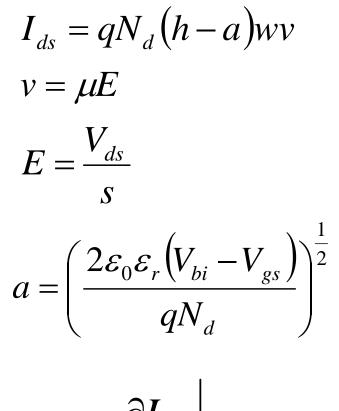
MMIC Design and Technology Active Devices

Instructor: Dr. Ali Medi

MESFET Operation



$$g_m = \frac{\partial I_{ds}}{\partial V_{gs}}\Big|_{V_{ds} = Const}$$

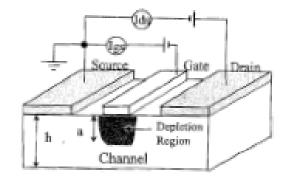


Figure 2.31 Schematic of a MESFET

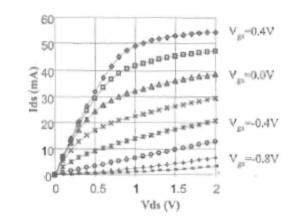


Figure 2.33 Output characteristics of a MESFET

MESFET Equivalent Circuit

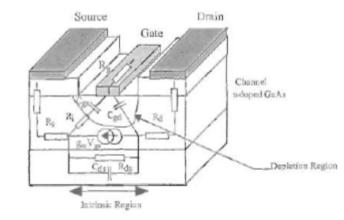
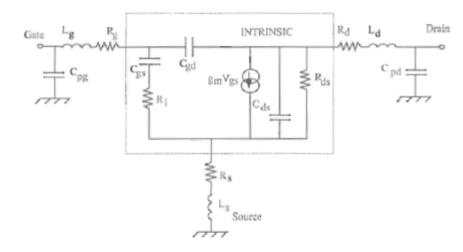


Figure 2.34 Cross-section of MESFET with superimposed lumped-element equivalent circuit



$$g_m = \frac{\partial I_{ds}}{\partial V_{gs}} \bigg|_{V_{ds} = Const}$$

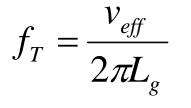
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Figure 2.35 Lumped-element equivalent circuit of a MESFET

Frequency

$$f_T = \frac{g_m}{2\pi (C_{gs} + C_{gd})}$$

Cut off Frequency where $I_{ds} = I_{gs}$

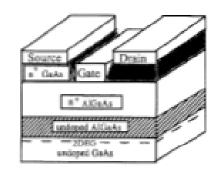


 $f_T = \frac{v_{eff}}{2\pi L_g}$ For High frequency Increase effective velocity For High frequency and reduce gate lengths

$$f_T = \frac{g_m}{2\pi \left[\left(C_{gs} + C_{gd} \right) \left(1 + \frac{R_s + R_d}{R_{ds}} \right) + g_m C_{gd} \left(R_s + R_d \right) \right]}$$

And minimize resistance

HEMT and pHEMT



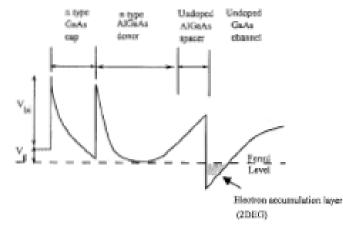


Figure 2.37 Cross-section of AlGaAs/GaAs HEMT and its conduction hand diagram

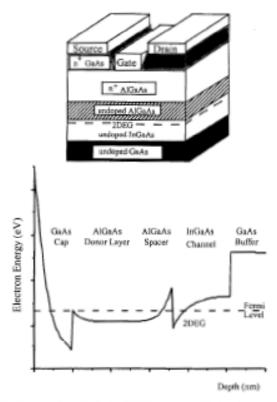


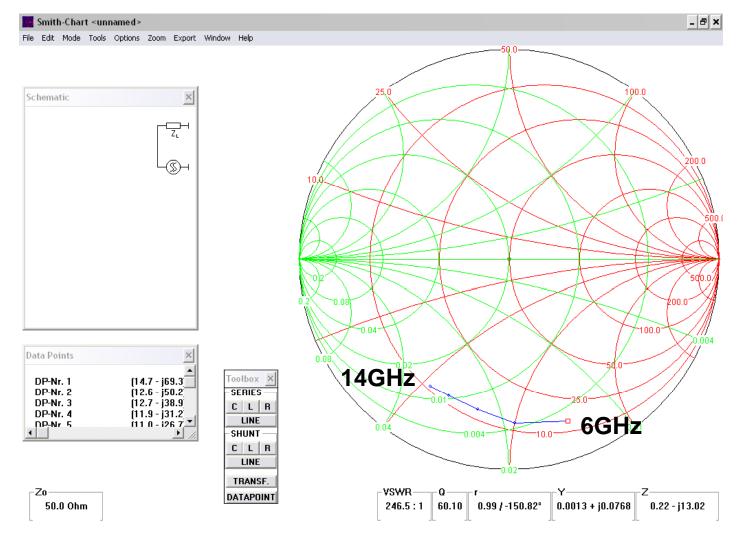
Figure 2.39 Cross-section of a GaAs pHEMT grown on a GaAs substrate and its conduction band diagram

Data file for actual device

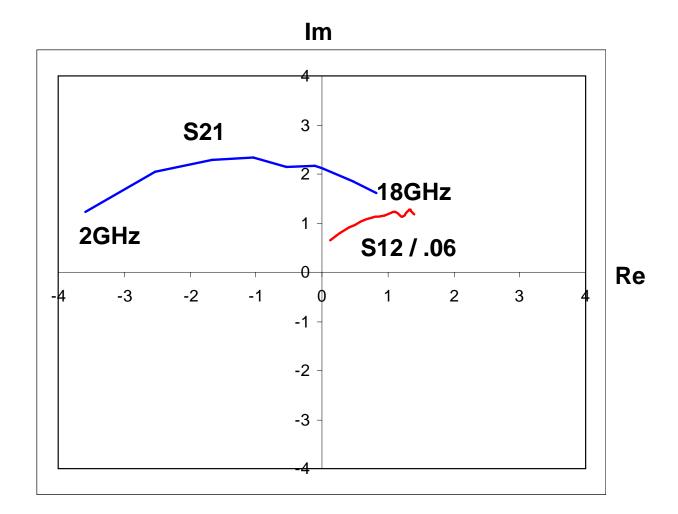
! FILENAME: N67300.S2P VERSION: 1.0
! NEC PART NUMBER: NE67300 DATE: 4/83
! BIAS CONDITIONS: VDS=3V, IDS=10mA
! NOTE : GATE AND DRAIN BOND WIRES ARE DE-EMBEDDED.
! NOTE : SOURCE BOND WIRE EFFECTS ARE INCLUDED. Ltotal = 0.07 nH
! (4 EACH 0.7 mil DIAMETER GOLD WIRES APPROXIMATELY 0.015" LONG).
GHZ S MA R 50

2	0.95	-26	3.79	161	0.04	79	0.59	-13
4	0.89	-50	3.26	141	0.06	66	0.58	-24
6	0.82	-70	2.83	126	0.08	56	0.54	-33
8	0.78	-88	2.55	114	0.09	51	0.5	-42
10	0.73	-102	2.21	104	0.1	48	0.47	-48
12	0.71	-114	2.16	93	0.1	43	0.45	-55
14	0.71	-122	2.11	90	0.11	44	0.47	-62
16	0.67	-128	1.92	76	0.11	43	0.49	-64
18	0.66	-140	1.81	63	0.11	40	0.52	-70
f1	ReS11	ImS11	ReS21	lmS21	ReS12	ImS12	ReS22	ImS22

S11 on Smith Chart



S21 and S12



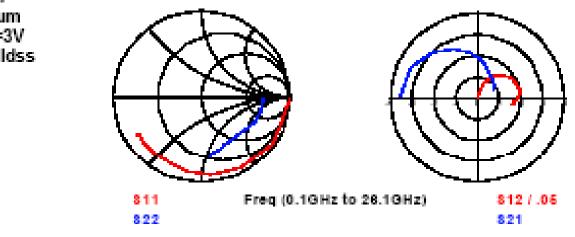
FET Example

Production Process



TQTRX MESFET Foundry Service

GFET 300 um Vds=3V 50% Idss



Input Reflection Coefficient

S11 is reflection coefficient only when port
 2 is terminated in a matched load

$$\begin{bmatrix} b_1 \\ b_2 \end{bmatrix} = \begin{bmatrix} S_{11} & S_{12} \\ S_{21} & S_{22} \end{bmatrix} \begin{bmatrix} a_1 \\ a_2 \end{bmatrix} \qquad \begin{array}{c} \mathbf{a1} \rightarrow \mathbf{b1} \leftarrow \mathbf{a2} \\ \mathbf{b1} \leftarrow \mathbf{b1} \leftarrow \mathbf{b2} & \Gamma_L \end{array}$$

$$\Gamma_{in} = \frac{b_1}{a_1} = S_{11} + \frac{S_{21}S_{12}\Gamma_L}{1 - S_{22}\Gamma_L} = S_{11} \text{ when } S_{12} = 0$$

Output Reflection Coefficient

S22 is reflection coefficient only when port
 1 is terminated in a matched load

$$\begin{bmatrix} b_1 \\ b_2 \end{bmatrix} = \begin{bmatrix} S_{11} & S_{12} \\ S_{21} & S_{22} \end{bmatrix} \begin{bmatrix} a_1 \\ a_2 \end{bmatrix} \qquad \begin{array}{c} \mathbf{a1} \rightarrow \mathbf{a1} \rightarrow \mathbf{a2} \\ \Gamma_s & \mathbf{b1} \leftarrow \mathbf{b2} \end{array} \qquad \begin{array}{c} \mathbf{a2} \\ \mathbf{b2} \end{array} \qquad \begin{array}{c} \mathbf{b1} \leftarrow \mathbf{b2} \end{array} \qquad \begin{array}{c} \mathbf{b2} \\ \mathbf{b2} \end{array} \qquad \begin{array}{c} \mathbf{b1} \\ \mathbf{b1} \end{array} \qquad \begin{array}{c} \mathbf{b1} \\ \mathbf{b2} \end{array} \qquad \begin{array}{c} \mathbf{b1} \\ \mathbf{b1} \end{array} \qquad \begin{array}{c} \mathbf{b1} \\ \mathbf{b2} \end{array} \qquad \begin{array}{c} \mathbf{b1} \\ \mathbf{b1} \end{array} \qquad \begin{array}{c} \mathbf{b1} \\ \mathbf{b1} \end{array} \qquad \begin{array}{c} \mathbf{b1} \\ \mathbf{b2} \end{array} \qquad \begin{array}{c} \mathbf{b1} \\ \mathbf{b2} \end{array} \qquad \begin{array}{c} \mathbf{b1} \\ \mathbf{b1} \end{array} \qquad \begin{array}{c} \mathbf{b1} \end{array} \qquad \begin{array}{c} \mathbf{b1} \\ \mathbf{b1} \end{array} \qquad \begin{array}{c} \mathbf{b1} \end{array} \qquad \begin{array}{c}$$

$$\Gamma_{out} = \frac{b_2}{a_2} = S_{22} + \frac{S_{21}S_{12}\Gamma_s}{1 - S_{11}\Gamma_s} = S_{22} \text{ when } S_{12} = 0$$

Stability

• Transistor is unstable when $|\Gamma_{in}| > 1$

$$\Gamma_{in} = \frac{b_1}{a_1} = S_{11} + \frac{S_{21}S_{12}\Gamma_L}{1 - S_{22}\Gamma_L}$$

Boundary Condition for Stability

$$\left| S_{11} + \frac{S_{21}S_{12}\Gamma_L}{1 - S_{22}\Gamma_L} \right| = 1$$

Stability

• Transistor is unstable when $|\Gamma_{out}| > 1$

$$\Gamma_{out} = \frac{b_2}{a_2} = S_{22} + \frac{S_{21}S_{12}\Gamma_s}{1 - S_{11}\Gamma_s}$$

Boundary Condition for Stability

$$\left| S_{22} + \frac{S_{21}S_{12}\Gamma_s}{1 - S_{22}\Gamma_s} \right| = 1$$

Stability Circles on Smith Chart

 Load or Source stability circle is the locus of points in the $\Gamma_{\rm L}$ or $\Gamma_{\rm s}$ plane, for which Γ_{in} or $\Gamma_{out} = 1$. If the center of the smith chart is enclosed by the stability circle then all points inside the circle are stable. If the center is not enclosed then all points inside the circle are unstable.

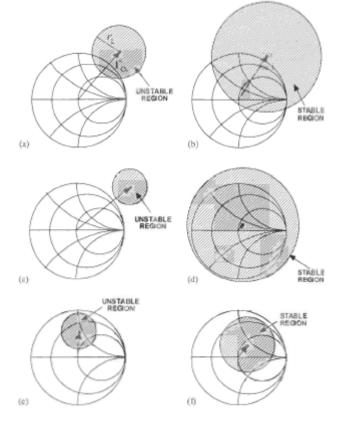


Figure 5.2 Stubility circles on the Smith chart: (a) stability circle partially inside the Smith chart, (b) partially inside and encompassing the 50 Ω point, (c) completely outside, (d) completely encompassing the Smith chart, (c) completely inside but not encompassing the 50 Ω point and (f) completely inside and encompassing the 50 Ω point

Unconditional Stability

 If all of the smith chart is in a stable region then the transistor is said to be unconditionally stable.

-
$$\Gamma_{in}$$
 or Γ_{out} <1 for all values of Γ_L or Γ_S

$$K = \frac{1 - |S_{11}|^2 - |S_{22}|^2 + |\Delta|^2}{2|S_{12}S_{21}|}$$
$$\Delta = S_{11}S_{22} - S_{12}S_{21}$$

Unconditionally Stable for K>1